East SUSPBUSPT, WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
1.1	6	lee-date\$	US-PGPUB; USPAT	OR	OFF	2005/08/19 18:04
L2	22633	(dougbuanam semiconductor).as.	US-PGPUB; USPAT	OR	OFF	2005/08/19 18:04
L3	555	(1 or 2) and "bonding pad"	US-PGPUB; USPAT	OR	OFF	2005/08/19 18:01
L4	10460	"bonding pad"	US-PGPUB; USPAT	OR	OFF	2005/08/19 18:04
L5	62488	"adhesive metal layer" or "adhesive layer"	US-PGPUB; USPAT	OR	ON	2005/08/19 18:04
L6	88649	"metal wire layer" or "metal layer"	US-PGPUB; USPAT	OR	ON	2005/08/19 18:04
L7	20	4 same 5 same 6	US-PGPUB; USPAT	OR	ON	2005/08/19 18:03
L8	3	(1 or 2) and 7	US-PGPUB; USPAT	OR	ON	2005/08/19 18:03
L9	0	lee-date\$	JPO; DERWENT	OR	OFF	2005/08/19 18:04
L10	66086	(dougbuanam semiconductor).as.	JPO; DERWENT	OR	OFF	2005/08/19 18:04
L11	9498	"bonding pad"	JPO; DERWENT	OR	OFF	2005/08/19 18:04
L12	71374	"adhesive metal layer" or "adhesive layer"	JPO; DERWENT	OR	ON	2005/08/19 18:04
L13	50360	"metal wire layer" or "metal layer"	JPO; DERWENT	OR	ON	2005/08/19 18:05
L14	3	10 and 11 and 12 and 13	JPO; DERWENT	OR	ON	2005/08/19 18:07
L15	1697865	etch\$ or patern\$ or remov\$	JPO; DERWENT	OR	ON	2005/08/19 18:08
L16	30	10 and 11 and 13 and 15	JPO; DERWENT	OR	ON	2005/08/19 18:07
L17	27	16 not 14	JPO; DERWENT	OR	ON	2005/08/19 18:07
L18	2491437	etch\$ or patern\$ or remov\$	US-PGPUB; USPAT	OR	ON	2005/08/19 18:08
L19	336	4 same 6 same 18	US-PGPUB; USPAT	OR	ON	2005/08/19 18:08
L20	38	(1 or 2) and 19	US-PGPUB; USPAT	OR	ON	2005/08/19 18:08
L21	35	20 not 8	US-PGPUB; USPAT	OR	ON	2005/08/19 18:08